



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC011N03LST	Issued	26. June 2021
MA#	MA005566220		
Package	PG-TDSON-8-26	Weight*	114.73 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.077	0.94	0.94	9385	9385
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		135	
	non noble metal	iron	7439-89-6	0.052	0.05		452	
	non noble metal	copper	7440-50-8	51.740	45.10	45.16	450994	451581
wire	noble metal	gold	7440-57-5	0.041	0.04	0.04	359	359
encapsulation	organic material	carbon black	1333-86-4	0.082	0.07		714	
	plastics	epoxy resin	-	6.470	5.64		56395	
	inorganic material	silicondioxide	60676-86-0	34.397	29.98	35.69	299820	356929
leadfinish	non noble metal	tin	7440-31-5	1.392	1.21	1.21	12129	12129
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1689	1689
solder	non noble metal	tin	7440-31-5	0.030	0.03		257	
	noble metal	silver	7440-22-4	0.037	0.03		322	
	non noble metal	lead	7439-92-1	1.410	1.23	1.29	12290	12869
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.02		150	
	noble metal	silver	7440-22-4	0.635	0.55		5539	
	non noble metal	copper	7440-50-8	17.131	14.93	15.50	149325	155059
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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